

# FDZ4670

## N-Channel PowerTrench® MOSFET BGA

### 30V, 25A, 2.5mΩ

#### Features

- Max  $r_{DS(on)}$  = 2.5mΩ at  $V_{GS} = 10V$ ,  $I_D = 25A$
- Max  $r_{DS(on)}$  = 4.5mΩ at  $V_{GS} = 4.5V$ ,  $I_D = 18.5A$
- Ultra-thin package: less than 0.85mm height when mounted to PCB
- Outstanding thermal transfer characteristics
- Ultra-low gate charge x  $r_{DS(on)}$  product
- RoHS Compliant



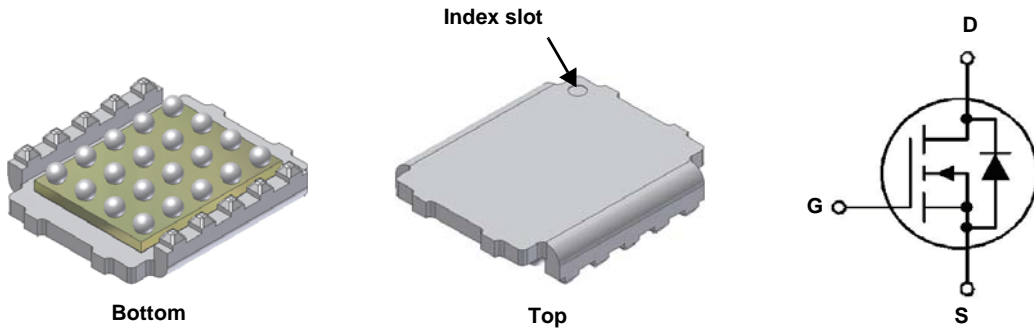
#### General Description

Combining Fairchild's 30V PowerTrench process with state-of-the-art BGA packaging, the FDZ4670 minimize both PCB space and  $r_{DS(on)}$ . This BGA MOSFET embodies a breakthrough in packaging technology which enables the device to combine excellent thermal transfer characteristics, high current handling capacity, ultra-low profile packaging, low gate charge and low  $r_{DS(on)}$ .

This MOSFET feature faster switching and lower gate charge than other MOSFETs with comparable  $r_{DS(on)}$  specifications resulting in DC/DC power supply designs and POL converters with higher overall efficiency.

#### Applications

- DC - DC Conversion
- POL converters



FLFBGA 3.5X4.0

#### MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rated	Units
$V_{DS}$	Drain to Source Voltage	30	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current -Continuous (Note 1a)	25	A
	-Pulsed	60	
$P_D$	Power Dissipation (Note 1a)	2.5	W
	Power Dissipation (Note 1b)	1.25	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

#### Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1b)	100	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.85	

#### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
4670	FDZ4670	FLFBGA 3.5X4.0	13"	12mm	3000 units

## Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , referenced to $25^\circ\text{C}$		-30		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			$\pm 100$	nA

### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1	1.7	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , referenced to $25^\circ\text{C}$		4.4		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 25\text{A}$		1.9	2.5	m $\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 18.5\text{A}$		3.0	4.5	
		$V_{GS} = 10\text{V}, I_D = 25\text{A}, T_J = 125^\circ\text{C}$		2.6	3.8	
$g_{FS}$	Forward Transconductance	$V_{DD} = 10\text{V}, I_D = 25\text{A}$		114		S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V},$ $f = 1\text{MHz}$		2660	3540	pF
$C_{oss}$	Output Capacitance			1440	1920	pF
$C_{rss}$	Reverse Transfer Capacitance			180	270	pF
$R_g$	Gate Resistance	$f = 1\text{MHz}$		1.0		$\Omega$

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{V}, I_D = 1.0\text{A},$ $V_{GS} = 10\text{V}, R_{GEN} = 6\Omega$		15	27	ns
$t_r$	Rise Time			11	20	ns
$t_{d(off)}$	Turn-Off Delay Time			50	80	ns
$t_f$	Fall Time			67	107	ns
$Q_g$	Total Gate Charge	$V_{GS} = 10\text{V}, V_{DD} = 15\text{V},$ $I_D = 25\text{A}$		40	56	nC
$Q_{gs}$	Gate to Source Charge			7		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			6		nC

### Drain-Source Diode Characteristics

$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 1.8\text{A}$ (Note 2)		0.7	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F = 25\text{A}, di/dt = 100\text{A}/\mu\text{s}$		46	69	ns
$Q_{rr}$	Reverse Recovery Charge			28	42	nC

#### NOTES:

1.  $R_{\theta JA}$  is determined with the device mounted on a 1in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta Jc}$  is determined by the user's board design.



a. 50°C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



b. 100°C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300 $\mu\text{s}$ , Duty cycle < 2.0%.

**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted

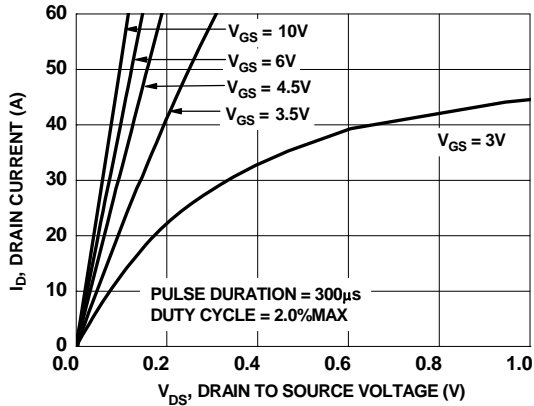


Figure 1. On-Region Characteristics

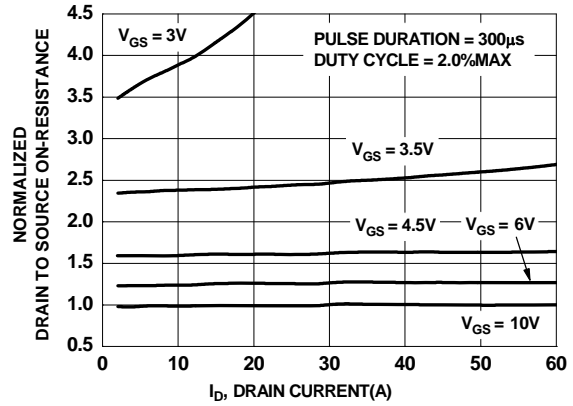


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

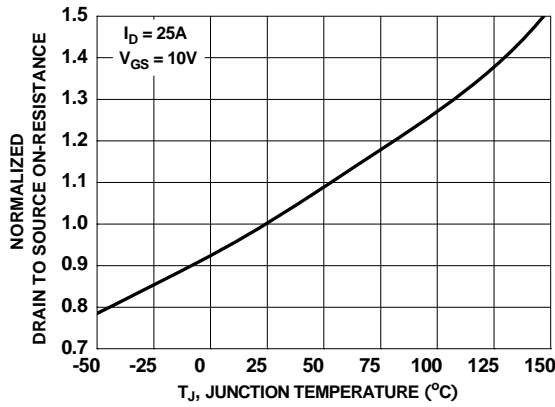


Figure 3. Normalized On-Resistance vs Junction Temperature

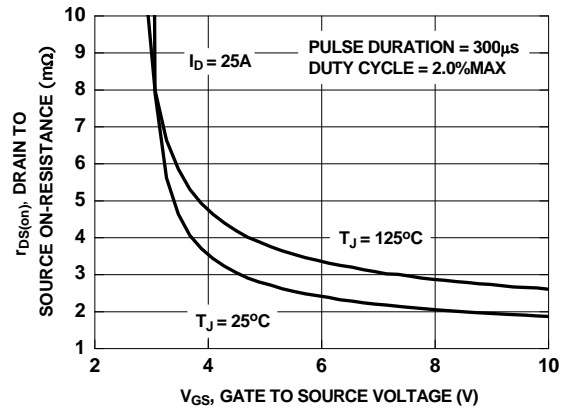


Figure 4. On-Resistance vs Gate to Source Voltage

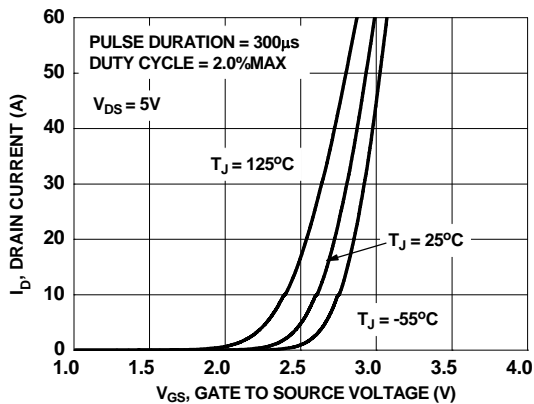


Figure 5. Transfer Characteristics

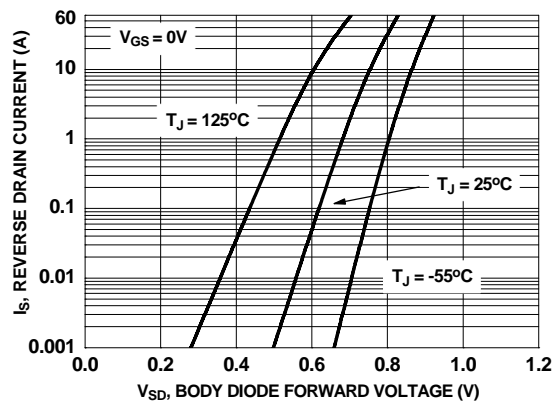
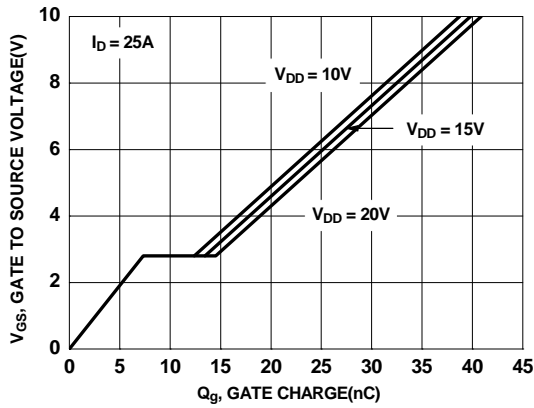
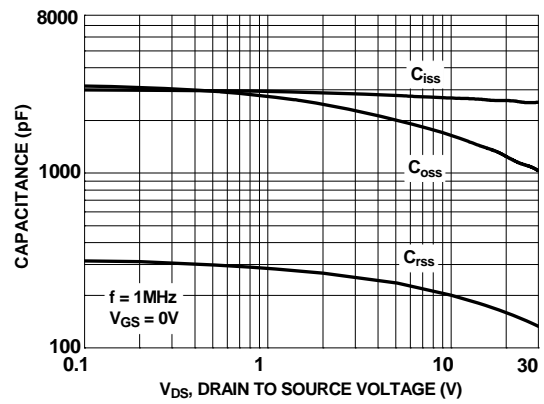


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

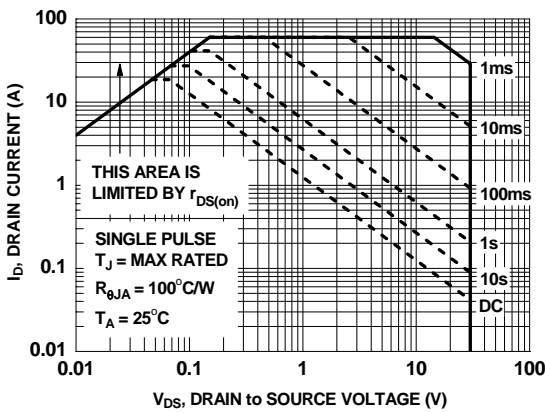
**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted



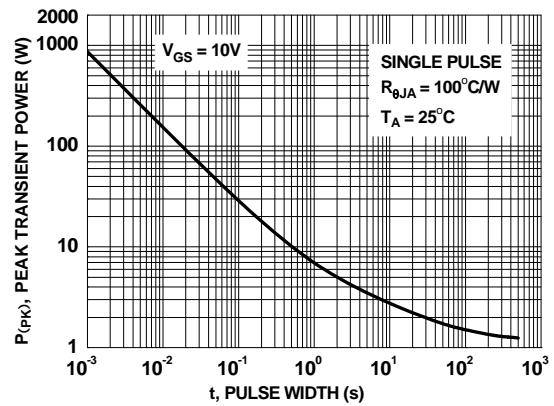
**Figure 7. Gate Charge Characteristics**



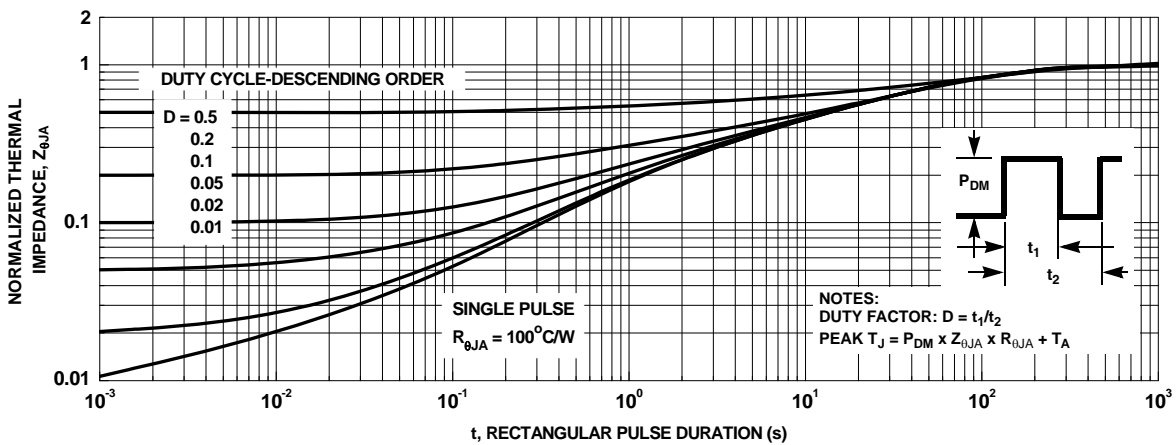
**Figure 8. Capacitance vs Drain to Source Voltage**



**Figure 9. Forward Bias Safe Operating Area**

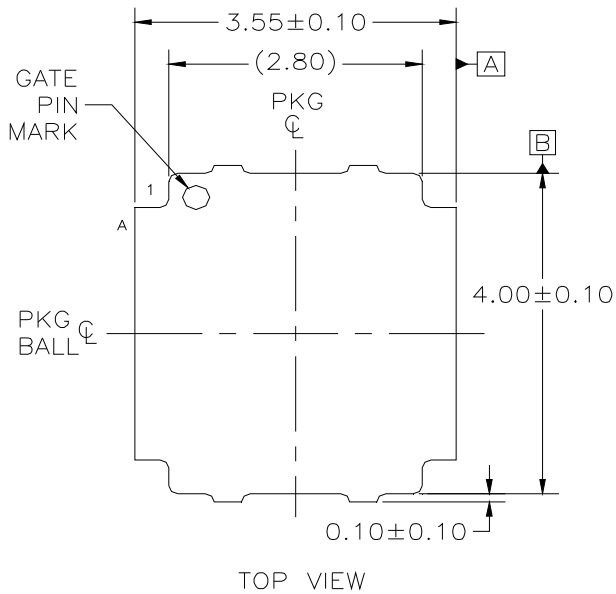


**Figure 10. Single Pulse Maximum Power Dissipation**

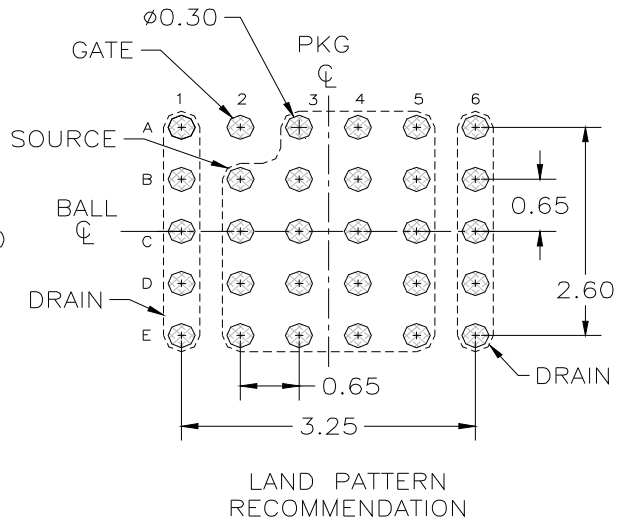


**Figure 11. Transient Thermal Response Curve**

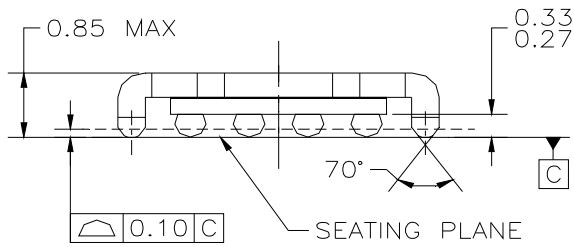
### Dimensional Outline and Pad Layout



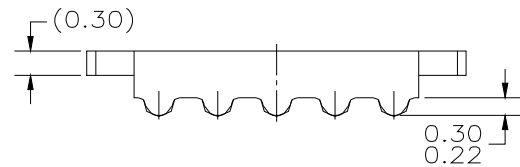
TOP VIEW



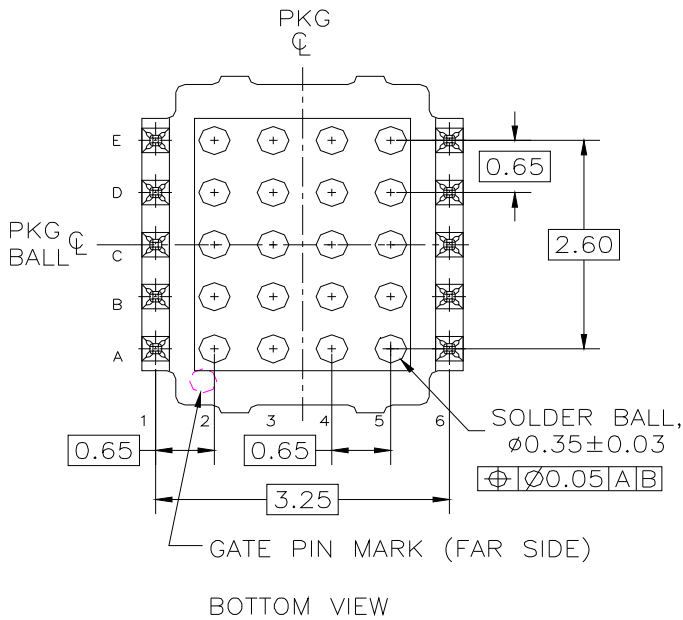
LAND PATTERN RECOMMENDATION



FRONT VIEW



SIDE VIEW



BOTTOM VIEW

BGA020CREVA


- NOTES: UNLESS OTHERWISE SPECIFIED  
 A) ALL DIMENSIONS ARE IN MILLIMETERS.  
 B) NO JEDEC REGISTRATION REFERENCE AS OF MARCH 2006.  
 C) TERMINAL CONFIGURATION TABLE

POSITION	DESIGNATION	TYPE
A1,B1,C1,D1,E1, A6,B6,C6,D6,E6	DRAIN	COPPER STUD
A2	GATE	SOLDER BALL
A3,A4,A5,B2,B3, B4,B5,C2,C3,C4, C5,D2,D3,D4,D5, E2,E3,E4,E5	SOURCE	SOLDER BALL



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DOMETM	MSXPro™	SMART START™	Wire™
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